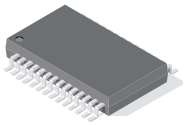
CCD VERTICAL DRIVER FOR DIGITAL CAMERAS

Check for Samples: VSP1900



FEATURES

- **CCD Vertical Driver:**
  - **Three Field CCD Support**
  - **Two Field CCD Support**
- **Output Drivers:**
  - **3 Levels Driver (V-Transfer) x 5**
  - **2 Levels Driver (V-Transfer) x 3**
  - **2 Levels Driver (E-Shutter) x 1**
- **Driver Capability:**
  - **450 pF to 1890 pF With 60 Ω to 240 Ω**
- **Input Phase:**
  - **3 State (V-Transfer) x 5**
  - **2 State (V-Transfer) x 3**
  - **2 State (E-Shutter) x 1**
- **Portable Operation**
  - **Input Interface: 2.7 V to 5.5 V**
- **Power Supply:**
  - **VDD 2.7 V to 5.5 V**
  - **VL –5 V to –9 V**
  - **VM GND**
  - **VH 11.5V to 15.5 V**

APPLICATIONS

- **Digital Camera**
- **Video Camera**

DESCRIPTION

The VSP1900 is a CCD vertical clock driver with electric-shutter support. This device is composed of eight vertical transfer channels, which support both 3-field CCD and 2-field CCD operation. The VSP1900 contributes low power consumption and device count reduction in the system.

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

PACKAGING ORDERING INFORMATION(1)

PRODUCT	PACKAGE	PACKAGE DESIGNATOR	OPERATING TEMPERATURE RANGE	PACKAGE MARKING	ORDER NUMBER	TRANSPORT MEDIA
VSP1900	TSSOP30	DBT	–25°C to 85°C	VSP1900	VSP1900	Tube (60 units per tube)

(1) For the most current specification and package information, refer to our web site at www.ti.com

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)(1)

		VALUES	UNIT
Supply voltage	VDD	GND –0.3 to 7	V
	VL	GND to –10	
	VH	VL + 26	
Input voltage, V_{IN}		GND –0.3 to (VDD + 0.3)	V
Ambient temperature under bias		–25 to 85	°C
Storage temperature, T_{stg}		–55 to 150	°C
Junction temperature, T_J		150	°C
Package temperature (IR reflow, peak)		260	°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
Supply voltage, VDD	2.7		5.5.	V
Supply voltage, VL	–5		–9	V
Supply voltage, VH	11.5		15.5	V
Input voltage, V_{IN}		GND –.03 to (VDD + 0.3)		V

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ELECTRICAL CHARACTERISTICS

All specifications at T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN(1)	TYP	MAX(1)	UNIT
DC power consumption				5.3		mW
Switching power consumption				550		mW
DC CHARACTERISTICS						
V_{IH}	High-level input voltage		0.7VDD			V
V_{IL}	Low-level input voltage				0.2VDD	V
I_{IN}	Input current	V_{IN} = GND to 5 V (without pullup or pulldown resistor)	–10	0	10	µA
		V_{IN} = GND to 5 V (pullup or pulldown resistor)	–625	0	625	
I_{IH}	Operating supply current			0.1	0.2	mA
I_{DD}				1		
I_{IL}				0.125		
I_{OL}	Output current	V1, V2, V3A, V3B, V4, V5A, V5B, V6 = –8.1 V	10			mA
I_{OM1}		V1, V2, V3A, V3B, V4, V5A, V5B, V6 = –0.2 V			–5	
I_{OM2}		V1, V3A, V3B, V5A, V5B = 0.2 V	5			
I_{OH}		V1, V3A, V3B, V5A, V5B = 14.55 V			–7.2	
I_{OSL}		SUB = –8.1 V	5.4			
I_{OSH}		SUB = 14.55 V			–4	

(1) Specified by design

SWITCHING CHARACTERISTICS

All specification at TA = 25°C (unless otherwise noted)

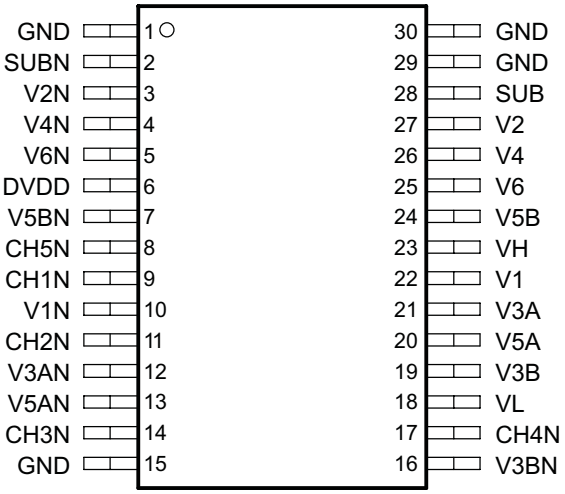
PARAMETER		TEST CONDITIONS	MIN(1)	TYP	MAX(1)	UNIT
$t_{d(PLM)}$	Propagation delay time			15	100	ns
$t_{d(PMH)}$				20	100	
$t_{d(PLH)}$				20	100	
$t_{d(PML)}$				15	50	
$t_{d(PHM)}$				30	50	
$t_{d(PHL)}$				30	50	
$t_{r(TLM)}$	Rise time	VL → VM			300	ns
$t_{r(TMH)}$		VM → VH			300	
$t_{r(TLH)}$		VL → VH			300	
$t_{f(TML)}$	Fall time	VM → VL			300	ns
$t_{f(THM)}$		VH → VM			300	
$t_{f(THL)}$		VH → VL			300	
$V_{n(CLH)}$	Output noise voltage				2	V
$V_{n(CLL)}$						
$V_{n(CMH)}$						
$V_{n(CML)}$						
$V_{n(CHL)}$						

(1) Specified by design

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PIN ASSIGNMENTS

DBT PACKAGE
(TOP VIEW)

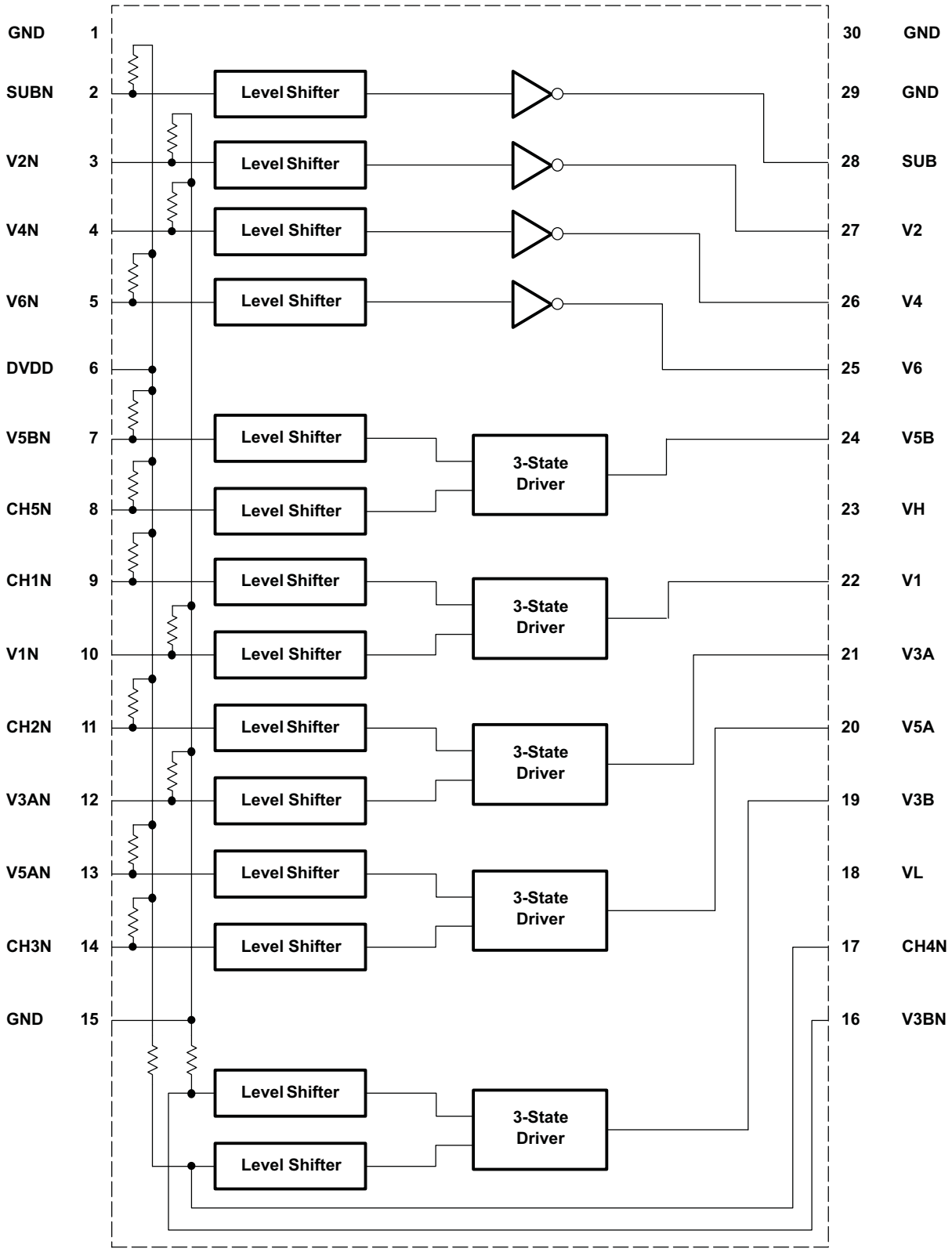


TERMINAL FUNCTIONS

TERMINAL		TYPE	DESCRIPTION
NAME	NO.		
GND	1, 15, 29, 30	P	Ground
SUBN	2	DI	CCD substrate clock SUB input
V2N	3	DI	Vertical transfer clock 2 input
V4N	4	DI	Vertical transfer clock 4 input
V6N	5	DI	Vertical transfer clock 6 input
DVDD	6	P	Digital power supply
V5BN	7	DI	Vertical transfer clock 5B input
CH5N	8	DI	Read out clock 5 input
CH1N	9	DI	Read out clock 1 input
V1N	10	DI	Vertical transfer clock 1 input
CH2N	11	DI	Read out clock 2 input
V3AN	12	DI	Vertical transfer clock 3A input
V5AN	13	DI	Vertical transfer clock 5A input
CH3N	14	DI	Read out clock 3 input
V3BN	16	DI	Vertical transfer clock 3B input
CH4N	17	DI	Read out clock 4 input
VL	18	P	Output driver power supply
V3B	19	DO	Vertical transfer clock 3B output
V5A	20	DO	Vertical transfer clock 5A output
V3A	21	DO	Vertical transfer clock 3A output
V1	22	DO	Vertical transfer clock 1 output
VH	23	P	Output driver power supply
V5B	24	DO	Vertical transfer clock 5B output
V6	25	DO	Vertical transfer clock 6 output
V4	26	DO	Vertical transfer clock 4 output
V2	27	DO	Vertical transfer clock 2 output
SUB	28	DO	CCD substrate clock SUB output

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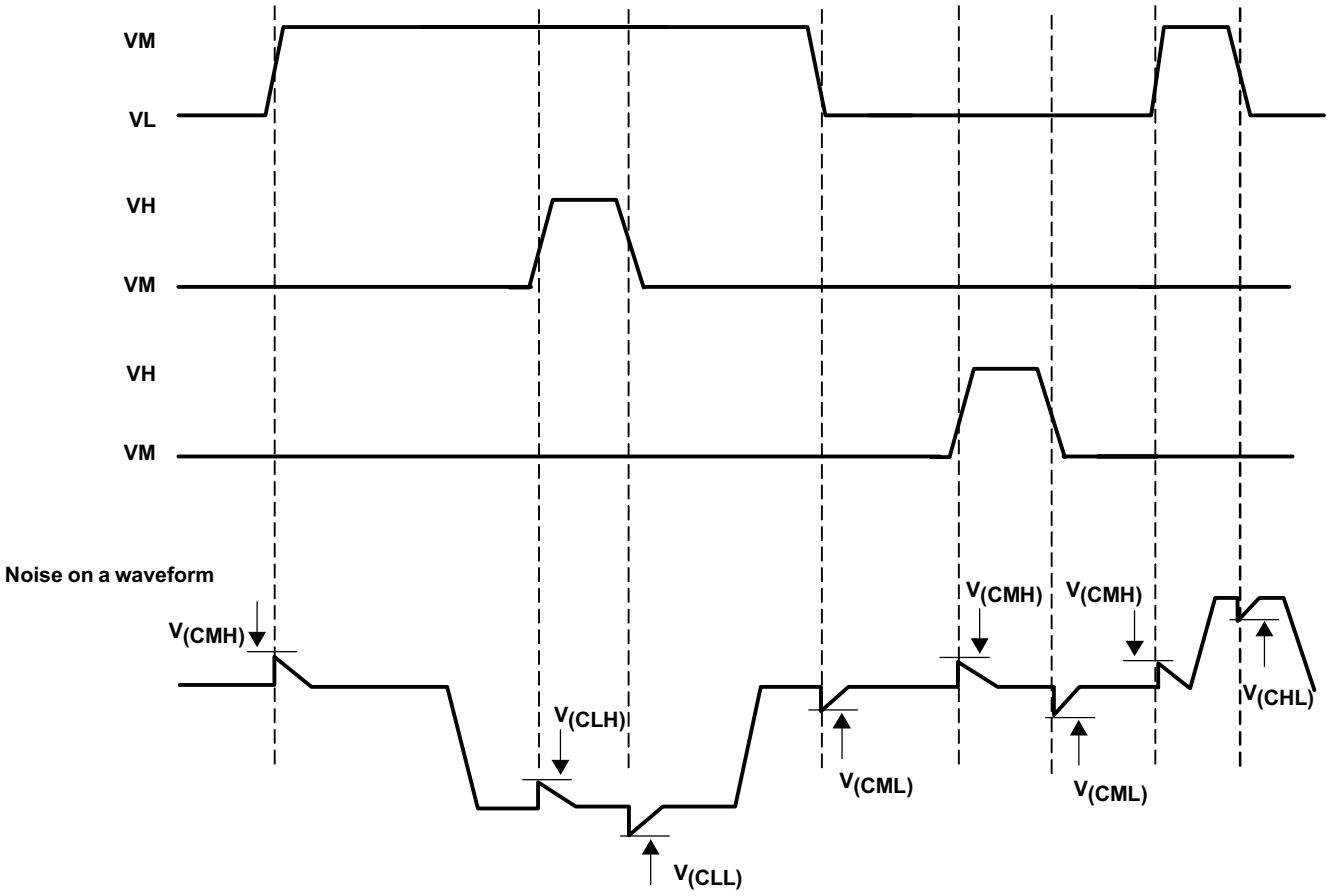
FUNCTIONAL BLOCK DIAGRAM



TRUTH TABLE

INPUT				OUTPUT		
V1N V3AN V3BN V5AN V5BN	CH1N CH2N CH4N CH3N CH5N	 V2N V4N V6N	 SUBN	V1 V3A V3B V5A V5B	 V2 V4 V6	 SUBN
L	L	X	X	VH	X	X
L	H	X	X	VM	X	X
H	L	X	X	Z	X	X
H	H	X	X	VL	X	X
X	X	L	X	X	VM	X
X	X	H	X	X	VL	X
X	X	X	L	X	X	VH
X	X	X	H	X	X	VL

SWITCHING WAVEFORM



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LOADING DIAGRAM

Vertical clock series resistor	R1, R2, R4, R6	60 Ω
	R3A, R5A	240 Ω
	R3B, R5B	80 Ω
Vertical clock to GND	CΦV1	1280 pF
	CΦV3A, CΦV3B	640 pF
	CΦV5A, CΦV5B	640 pF
	CΦV2, CΦV4, CΦV6	400 pF
Between vertical clock	CΦV12	510 pF
	CΦV23A, CΦV23B	50 pF
	CΦV45A, CΦV45B	50 pF
	CΦV3A4, CΦV3B4	260 pF
	CΦV5A6, CΦV5B6	260 pF
	CΦV61	100 pF
Substrate clock to GND	CΦVSUB	1000 pF
Vertical clock GND resistor	R GND	18 Ω

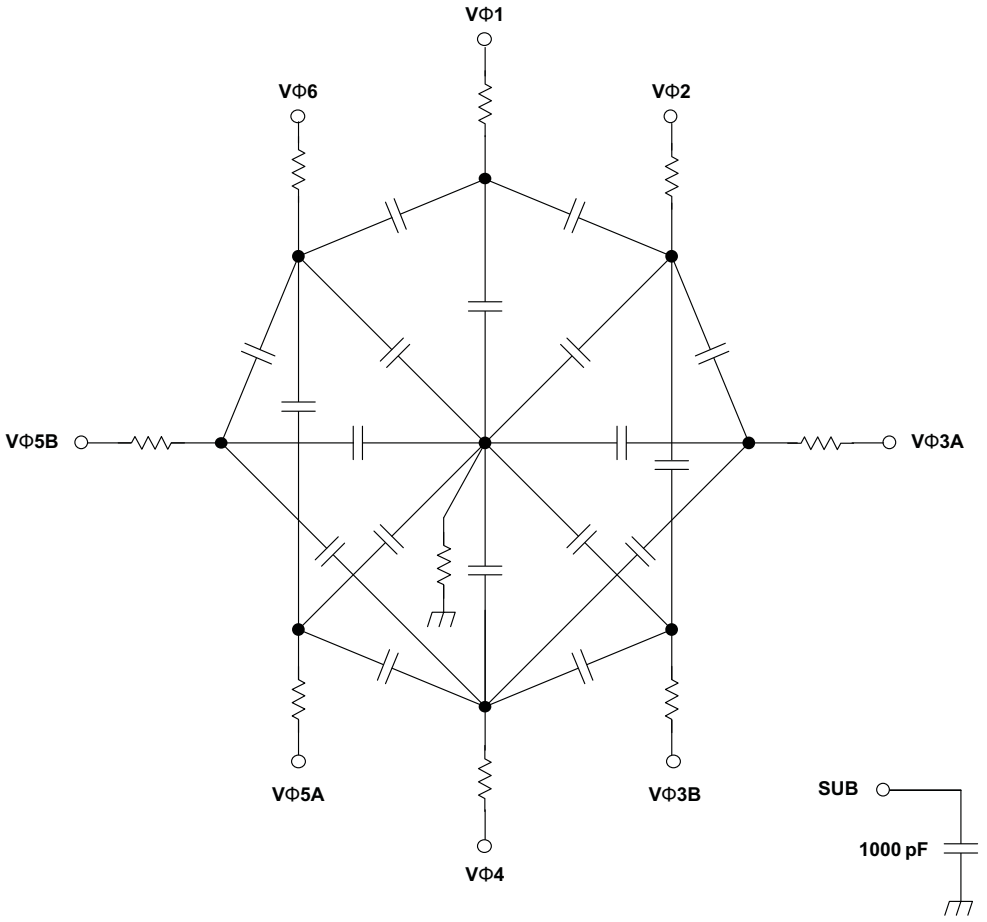


Figure 1. VSP1900 Loading Diagram

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DESCRIPTION

The VSP1900 is a CCD vertical clock driver with electric shutter. The VSP1900 is composed of five 3-state and three 2-state vertical transfer channels, which support both 3 field and 2 field CCD operation. The VSP1900 contributes low power consumption and parts number reduction in the system.

OPERATION

Power On/Off Sequence

This is the same as the CCD power up sequence, when power on, VDD powers on first VH, VM powers on second, and VL powers on later. When powering off, VL powers off first, VH, VM powers off second, and VDD powers off later.

Vertical Transfer Signal

The VSP1900 receives signals from TG (CCD timing generator). The input signal is converted into the operating voltage levels of the CCD by the level shifter. The level shifter circuits connect to a 2-state or 3-state driver, which is connected to the CCD input pin. While using a 2-field CCD, one of the 3-state drivers is used as a 2-state driver. The CH#N pin is pulled up internally, so that the VH level does not appear on the output pin.

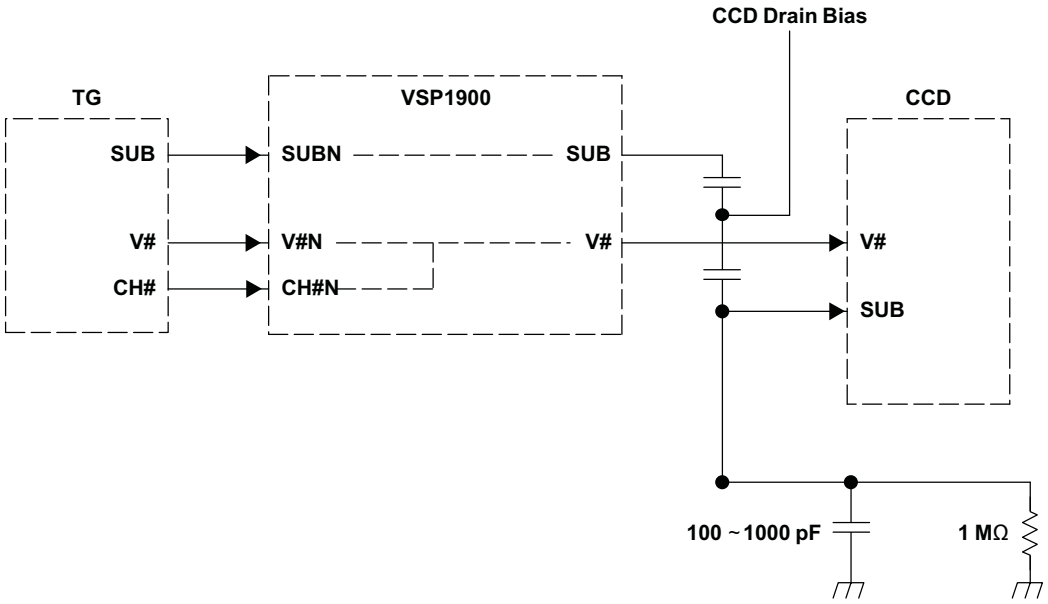


Figure 2. VSP1900 Circuit Application

REVISION HISTORY

Changes from Original (March 2003) to Revision A	Page
• Changed the last sentence of the Description From: "part number reduction in the system." To: " device count reduction in the system.	1
• Deleted the Tape and reel option from the Ordering Information Table	2
• Changed the Package temperature value From 2.35°C to 260°C	2
• Added Table Note " Specified by Design" to the MIN and MAX columns of the ELECTRICAL CHARACTERISTICS and SWITCHING CHARACTERISTICS.	3
• Changed the Truth Table	6

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
VSP1900DBT	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 85	VSP1900	Samples
VSP1900DBTG4	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 85	VSP1900	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

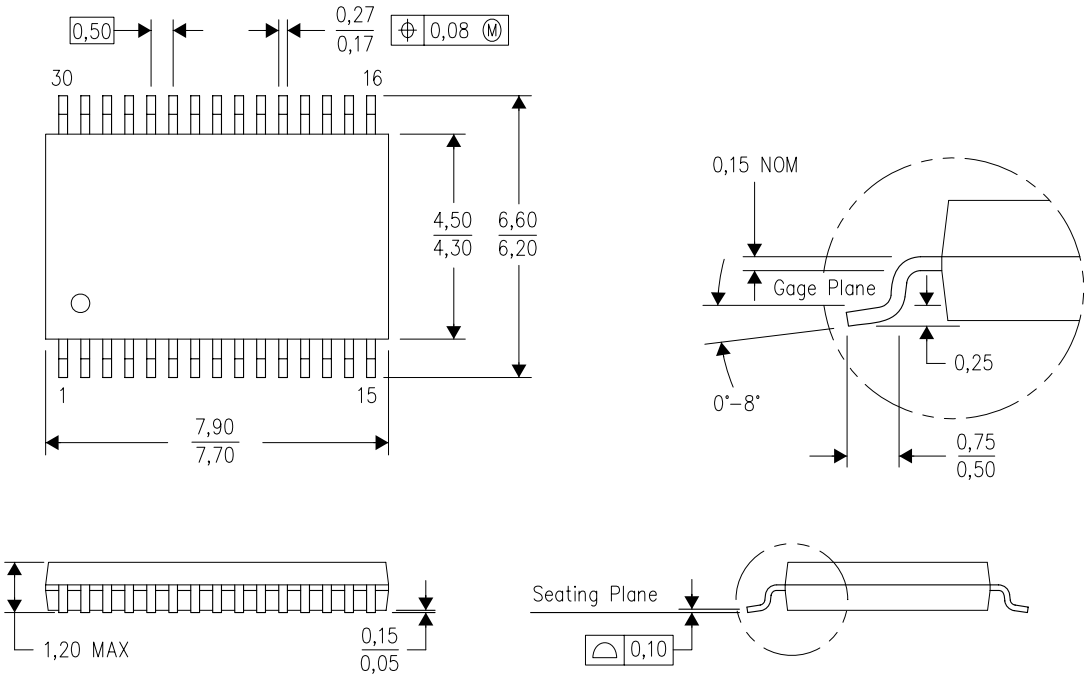
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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DBT (R–PDSO–G30) PLASTIC SMALL OUTLINE



4073252–5/I 03/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion.
D. Falls within JEDEC MO–153.

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